

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

1t3509ide#pbf

(Engineering Calculation)

DFN 4mm X 3mm Exp. Pad

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**TOTAL MASS (g) : 0.03118**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.001320	1000000	42335.1445312		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.013133	975000	421202.59375		
		Iron (Fe)	7439-89-6	0.000323	24000	10359.2802734		
		Phosphorus (P)	7723-14-0	0.000004	300	128.288314819		
		Zinc (Zn)	7440-66-6	0.000009	700	288.648712158		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.013469</b>	<b>1000000</b>	<b>431978.84375</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.000626	1000000	20069.703125		
		<b>External Plating Total:</b>				<b>0.000626</b>	<b>1000000</b>	<b>20069.703125</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000302	1000000	9685.76757812		
<b>Internal Plating Total:</b>				<b>0.000302</b>	<b>1000000</b>	<b>9685.76757812</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000704	750000	22578.7441406		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000235	250000	7536.93847656		
<b>Die Attach Total:</b>				<b>0.000939</b>	<b>1000000</b>	<b>30115.6816406</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.001876	130000	60167.21875		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.012410	860000	398014.5		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000144	10000	4618.37939453		
		<b>Encapsulation Total:</b>				<b>0.014430</b>	<b>1000000</b>	<b>462800.125</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000094	1000000	3014.77539062		
					<b>TOTAL MASS (g) :</b>	<b>0.03118</b>		